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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3747
Number of Logic Elements/Cells	89178
Total RAM Bits	6839296
Number of I/O	260
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	572-BGA, FCBGA
Supplier Device Package	572-FBGA, FC (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx95df25c4n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

pushPIN™ Heat Sink Assembly

ATS Part#: ATS-20B-17-C2-R0

Description: pushPIN™ HS ASMBLY,FINE-PITCH,XCUT, HOLE PATTERN:4-CORNER,BLUE,T766

Heat Sink Type: pushPIN™ Heat Sink Assembly

Heat Sink Attachment: pushPIN™

Features & Benefits

- » Quick Attachment Push pins feature a flexible barb at the end designed to engage with pre-drilled holes in a PCB.
- » Compression Springs add the necessary force to hold the assembly together for secure attachment. Select from over 21 different springs to achieve precise force required.
- » Push Pin Material available in brass or plastic in 10 sizes ranging from 9-20mm in length. Stainless steel hardware kit available for more secure attachment. Visit www.qats.com for available options.
- » Heat Sinks Designed for All Airflow Conditions. Select from over 112 fine pitch HS designed for high velocity air flows and 98 course pitch HS designed for low velocity air flow conditions.
- » Pre-assembled with phase-changing material for increased thermal performance. Double-sided thermal tape and no TIM options available to meet application-specific requirements.
- » Lightweight, aluminum HS extruded from AL6063 provide optimal heat transfer with a blue anodized finish.
- » All components are RoHS and REACH compliant.
- » Industry standard hole pattern. Recommended through hole size is 3.175mm



Bill of Material				
Heat Sink:	1			
Push Pin:	ATS-PP-02	2		
Springs:	ATS-PPS-20	2		

Thermal Performance

AIR VELOCITY	100 (0.5)	200 (1.0)	300 (1.5)	400 (2.0)	500 (2.5)	600 (3.0)	700 (3.5)	
Thermal Resistance °C/W	Unducted Flow	15.44	6.18	3.36	2.29	1.76	1.47	1.28
	Ducted Flow	2.18	1.33	1.06	0.92	0.84	0.77	0.73

Fin	Fin	Hole
Pitch	Type	Pattern
FINE-PITCH	XCUT	

Product Detail

P/N	Dimensions					Push Pin	Carina	TIM	Finish
	А	В	С	Е	F	PusiiPiii	Spring	I IIVI	FIIIISII
ATS-20B-17-C2-R0	54.00	54.00	12.70	47.00	47.00	ATS-PP-02	ATS-PPS-20	T766	BLUE ANODIZED



NOTES:

- 1) Dimension A is the length of the heat sink in the direction of the flow.
- 2) Dimension B is the width of the heat sink perpendicular to the flow direction.
- 3) Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- 4) Dimension E is the distance between holes perpendicular to the direction of flow.
- 5) Dimension F is the distance between holes in the direction of flow.
- 6) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 7) ATS reserves the right tp update or change its products without notice to improve the design or performance.
- 8) ATS certifies that this heat sink assemby is RoHS-6 and REACH compliant.
- 9) Contact ATS to learn about custom options available.



For further technical information, please contact Advanced Thermal Solutions, Inc.